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38525 WOODWARD AVENUE, SUITE 2000
BLOOMFIELD HILLS, MI 48304-2970
TELEPHONE: (248) 433-7200
FACSIMILE: ()
<http://www.dickinsonwright.com>

CONFIRMATION ☐

TO: Examiner Dilinh P. Nguyen	COMPANY: USPTO G.A.U. 2814
FAX NUMBER: 703-308-7382	PHONE NUMBER: 703-305-6983

From: Thomas T. Moga

Date: October 1, 2003

Total Number of Pages Including Cover Sheet: 03

Message:

Dear Examiner Nguyen:

The attached PROPOSED AMENDMENT relates to USSN 09/746,018. The last Office Action was a final Office Action. The client is considering filing an RCE on this case but asked if I could get a preliminary opinion from you as to the likely allowability of the attached draft claims.

Kindly review these claims and call me at your earliest opportunity at 248-433-7552.

Thank you.

Thomas T. Moga

248-433-7552

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OFFICE CODE

Client Name: Tsai Lee & Chen
Client/Matter Number: 046599-00254
Attorney Number: [1114]
Secretary/Ext.: Tina Tomayko/7545

Matter Name:
Attorney Initials: TTM
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DETROIT BLOOMFIELD HILLS LANSING GRAND RAPIDS ANN ARBOR WASHINGTON, D.C.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : 09/746,018 Confirmation No. 2272
Applicants : Jung-Yu Lee et al.
Filed : December 26, 2000
TC/A.U. : 2814
Examiner : Dilinh P. Nguyen

Docket No. : 046599-00254 (former docket no. 147268.00254)
Customer No. : 29381

**PROPOSED AMENDMENT FOR DISCUSSION
PURPOSES ONLY -
NOT TO BE ENTERED**

Sir:

In response to the Office Action mailed July 1, 2003, please consider the following proposed amendment which Applicants request not be entered at this time:

Claim 7 (currently amended) A semiconductor package, comprising:

a substrate;

a die located and supported on said substrate with an adhesive layer between them;

a plurality of signal transferring means which electrically connects said die to said substrate;

a molding compound which seals and protect said die and said plurality of signal transferring means, wherein said molding compound has geometrically a ~~concave~~ recessed portion located at the top surface of the center part, wherein said die is located right below said recessed portion and fully covered by said molding means, so that the thickness of said molding

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